

Title (en)
METHOD FOR GLUING FPCB'S

Title (de)
VERFAHREN ZUR VERKLEBUNG VON FPCB'S

Title (fr)
PROCEDE DE COLLAGE DE CARTES DE CIRCUITS IMPRIMES FLEXIBLES

Publication
EP 1590416 A1 20051102 (DE)

Application
EP 03782461 A 20031219

Priority
• EP 0314622 W 20031219
• DE 10303518 A 20030129
• DE 10317403 A 20030530

Abstract (en)
[origin: WO2004067665A1] The invention relates to the gluing of plastic pieces, in particular, Flexible Printed Circuit Boards (FPCB's). According to the invention, a thermally-activated adhesive is used for the gluing, comprising (i) at least one thermoplastic polymer or a modified rubber and (ii) at least one resin, preferably comprising at least one phenol resin and at least one epoxy resin.

IPC 1-7
C09J 7/02; **C08J 5/18**

IPC 8 full level
C09J 5/06 (2006.01); **C09J 7/10** (2018.01); **H05K 3/38** (2006.01); **C08L 21/00** (2006.01); **C08L 23/00** (2006.01); **C08L 61/00** (2006.01); **C08L 63/00** (2006.01); **C08L 67/00** (2006.01); **C08L 75/04** (2006.01); **C08L 77/00** (2006.01); **H05K 1/00** (2006.01)

CPC (source: EP KR US)
B29C 65/48 (2013.01 - KR); **C09J 5/00** (2013.01 - KR); **C09J 5/06** (2013.01 - EP KR US); **C09J 7/00** (2013.01 - KR); **C09J 7/10** (2017.12 - EP US); **H05K 1/0393** (2013.01 - KR); **H05K 3/386** (2013.01 - EP KR US); **C08L 21/00** (2013.01 - EP US); **C08L 23/00** (2013.01 - EP US); **C08L 61/00** (2013.01 - EP US); **C08L 63/00** (2013.01 - EP US); **C08L 67/00** (2013.01 - EP US); **C08L 75/04** (2013.01 - EP US); **C08L 77/00** (2013.01 - EP US); **C09J 2421/00** (2013.01 - EP KR US); **C09J 2423/00** (2013.01 - EP KR US); **C09J 2461/00** (2013.01 - EP KR US); **C09J 2463/00** (2013.01 - EP US); **C09J 2467/00** (2013.01 - EP KR US); **C09J 2467/006** (2013.01 - EP US); **C09J 2475/00** (2013.01 - EP US); **C09J 2477/00** (2013.01 - EP US); **C09J 2479/086** (2013.01 - EP US); **H05K 1/0393** (2013.01 - EP US); **H05K 2201/0129** (2013.01 - EP KR US); **H05K 2201/0133** (2013.01 - EP US); **H05K 2201/0209** (2013.01 - EP US); **Y10T 428/31511** (2015.04 - EP US); **Y10T 428/31721** (2015.04 - EP US); **Y10T 428/31786** (2015.04 - EP US)

Citation (search report)
See references of WO 2004067665A1

Designated contracting state (EPC)
DE ES FR GB IT

DOCDB simple family (publication)
WO 2004067665 A1 20040812; AU 2003290101 A 20040823; EP 1590416 A1 20051102; JP 2007515496 A 20070614; KR 20050094049 A 20050926; US 2006088715 A1 20060427

DOCDB simple family (application)
EP 0314622 W 20031219; AU 2003290101 A 20031219; EP 03782461 A 20031219; JP 2004567323 A 20031219; KR 20057014082 A 20050729; US 54375303 A 20031219